

BQ2057、BQ2057x の高度なリニア充電管理 IC (1 セルおよび 2 セル対応リチウムイオン / リチウムポリマ向け)

1 特長

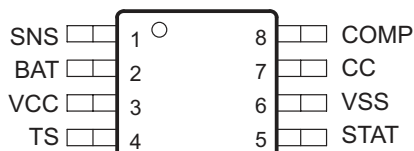
- 1 セル (4.1V または 4.2V) および 2 セル (8.2V または 8.4V) 対応のリチウムイオンまたはリチウムポリマ・パックに最適
- 必要な外部部品が少ない
- 放熱を最小限に抑える 0.3V ドロップアウト電圧
- プリセット電圧により電圧レギュレーション精度の誤差が $\pm 1\%$ 未満
- バッテリー・パックの内部インピーダンスの AutoCompM 動的補償で充電時間を短縮
- 充電前と充電中のセル温度監視オプション
- プログラマブル充電電流およびハイサイド / ローサイド電流検出を備えた電圧 / 電流レギュレーション機能を内蔵
- 深放電状態のセルを回復し、充電の初期段階で放熱を最小限に抑えるセル・コンディショニングを内蔵
- シングル / デュアル LED または ホスト・プロセッサ・インターフェイスの充電ステータス出力
- バッテリー自動再充電機能
- 最小電流による充電終了
- V_{CC} 除去時の自動低消費電力スリープ・モード
- EVM を利用した迅速な評価
- パッケージ: 8 ピン SOIC、8 ピン TSSOP、8 ピン MSOP

2 アプリケーション

- 緊急通報システム、テレマティクス制御ユニット
- アフターマーケット・テレマティクス
- ゲームおよびコンピュータ用アクセサリ
- 携帯医療機器
- EPOS カード・リーダー

3 概要

BQ2057 シリーズの高度なリチウムイオン (Li-ion) およびリチウムポリマ (Li-pol) リニア充電管理 IC は、コスト重視



BQ2057xSN または BQ2057xTS SOIC (SN) または TSSOP (TS) パッケージの上面図

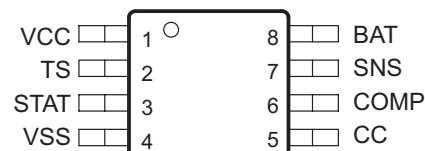
でコンパクトなポータブル・エレクトロニクス向けに設計されています。1 つの 8 ピン IC に、電流と電圧の高精度レギュレーション、バッテリー・コンディショニング、温度監視、充電終了、充電ステータス表示、AutoComp™ 充電率補償が統合されています。MSOP、TSSOP、SOIC の各パッケージ・オプションは、幅広いエンド・アプリケーションに対応しています。

BQ2057 は、外部サーミスタを使用してバッテリー温度を継続的に測定します。安全のため、バッテリー温度がユーザー定義のスレッシュホールド内になるまで充電は禁止されます。バッテリーの充電は、コンディショニング、定電流、定電圧の 3 つのフェーズで行われます。バッテリー電圧が低電圧スレッシュホールド $V_{(min)}$ を下回った場合、低電流を使用した事前充電によってバッテリーのコンディショニングが行われます。コンディショニング充電速度は、レギュレーション電流の約 10% です。また、コンディショニング電流により、充電の初期段階での外部バス素子の放熱も最小限に抑えられます。コンディショニング後、バッテリーに定電流が供給されます。電流は、外部センス抵抗によって設定されます。センス抵抗は、追加部品なしで、バッテリーのハイサイドまたはローサイドに配置できます。定電流フェーズは、バッテリーが充電レギュレーション電圧に達するまで続きます。

デバイス情報

部品番号	パッケージ (1)	本体サイズ (公称)
BQ2057C、BQ2057W	SOIC (8)	4.90mm × 3.91mm
BQ2057、BQ2057C、BQ2057T、BQ2057W	TSSOP (8)	3.00mm × 4.40mm
BQ2057、BQ2057C	MSOP (8)(2)	3.00mm × 3.00mm

- (1) 利用可能なすべてのパッケージについては、このデータシートの末尾にある注文情報を参照してください。
- (2) このデバイスのピン配置の違いに注意してください。



BQ2057xDGK MSOP DGK パッケージの上面図



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4 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision F (July 2002) to Revision G (December 2022)	Page
• 「ESD 定格」の表、「機能説明」セクション、「デバイスの機能モード」セクション、「アプリケーションと実装」セクション、「電源に関する推奨事項」セクション、「レイアウト」セクション、「デバイスおよびドキュメントのサポート」セクション、「メカニカル、パッケージ、および注文情報」セクションを追加.....	1
• Updated Device Comparison Table.....	4
• Added thermal information.....	5
• Added typical characteristics curves.....	8
• Added figure to セクション 10.2	22
• Added design requirements.....	22
• Added application curves.....	23
• Added Layout Guidelines subsections.....	25
• Added layout example.....	26

5 概要 (続き)

その後、定電圧フェーズが開始されます。電圧レギュレーションの精度は、動作温度および電源電圧範囲全体にわたって誤差 $\pm 1\%$ 未満です。1 セルおよび 2 セル向けに、BQ2057 は 4.1V、4.2V、8.2V、8.4V の 4 つの固定電圧バージョンで提供されます。充電終了スレッショルド $I_{(Term)}$ に電流が近づくと充電は停止します。バッテリー電圧が $V_{(RCH)}$ スレッショルドを下回ると、自動的に充電が再開されます。

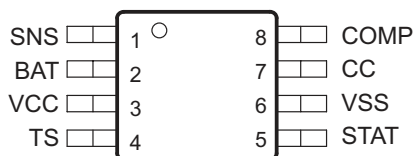
設計者は AutoComp 機能を使用して充電時間を短縮することもできます。この独自の手法により、充電中のバッテリー・パックの内部インピーダンスを安全かつ動的に補償できます。

6 Device Comparison Table

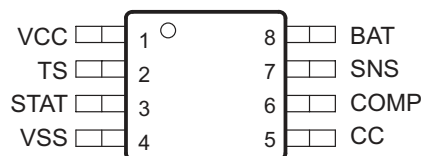
T _A	PACKAGE			
	CHARGE REGULATION VOLTAGE	SOIC (SN)	TSSOP (TS)	MSOP ⁽¹⁾ (DGK)
-20°C to 70°C	4.1 V	BQ2057SN	BQ2057TS	BQ2057DGK
	4.2 V	BQ2057CSN	BQ2057CTS	BQ2057CDGK
	8.2 V	BQ2057TSN	BQ2057TTS	Not available
	8.4 V	BQ2057WSN	BQ2057WTS	

(1) Note the difference in pinout for this package.

7 Pin Configuration and Functions



☒ 7-1. BQ2057xSN or BQ2057xTS SOIC (SN) or TSSOP (TS) Package Top View



☒ 7-2. BQ2057xDGK MSOP DGK Package Top View

表 7-1. Pin Functions-

NAME	PIN NO.		I/O	DESCRIPTION
	NO.			
	SOIC (SN) and TSSOP (TS)	MSOP (DGK)		
BAT	2	8	I	Voltage sense input
CC	7	5	O	Charge control output
COMP	8	6	I	Charge-rate compensation input (AutoComp)
SNS	1	7	I	Current sense input
STAT	5	3	O	Charge status output
TS	4	2	I	Temperature sense input
VCC	3	1	I	Supply voltage
VSS	6	4	-	Ground

8 Specifications

8.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

	MIN	MAX	UNIT
Supply voltage (V_{CC} with respect to GND)	-0.3	18	V
Input voltage, SNS, BAT, TS, COMP (all with respect to GND)	-0.3	$V_{CC}+0.3$	V
Sink current (STAT pin) not to exceed P_D		20	mA
Source current (STAT pin) not to exceed P_D		10	mA
Output current (CC pin) not to exceed P_D		40	mA
P_D Total power dissipation (at 25°C)		300	mW
T_A Operating free-air temperature range	-20	70	°C
T_{stg} Storage temperature	-40	125	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

8.2 ESD Ratings

		VALUE	UNIT
$V_{(ESD)}$ Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000	V
	Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±500	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

8.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

	MIN	NOM	MAX	UNIT
V_{CC} Supply voltage	4.5		15	V
T_A Operating free-air temperature range	-20		70	°C

8.4 Thermal Information

THERMAL METRIC ⁽¹⁾	BQ2057xSN or BQ2057xTS	BQ2057xDGK MSOP	UNIT
	SOIC (SN) or TSSOP (TS) PACKAGE	DGK PACKAGE	
	8 PINS	8 PINS	
$R_{\theta JA}$ Junction-to-ambient thermal resistance	157.1	121.9	°C/W
$R_{\theta JC(top)}$ Junction-to-case (top) thermal resistance	46.5	58.8	°C/W
$R_{\theta JB}$ Junction-to-board thermal resistance	89.6	65.8	°C/W
Ψ_{JT} Junction-to-top characterization parameter	3.3	12.8	°C/W
Ψ_{JB} Junction-to-board characterization parameter	87.4	65.0	°C/W
$R_{\theta JC(bot)}$ Junction-to-case (bottom) thermal resistance	NA	NA	°C/W

- (1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

8.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$I_{(VCC)}$	V_{CC} Current	$V_{CC} > V_{CC(min)}$, Excluding external loads		2	4	mA
$I_{(VCCS)}$	V_{CC} Sleep current	For BQ2057 and BQ2957C, $V_{(BAT)} \geq V_{(min)}$, $V_{(BAT)} - V_{CC} \geq 0.8$ V		3	6	μ A
		For BQ2057T and BQ2957W, $V_{(BAT)} \geq V_{(min)}$, $V_{(BAT)} - V_{CC} \geq 0.8$ V			10	
$I_{(BAT)}$	Input bias current on BAT pin	$V_{(BAT)} = V_{(REG)}$			1	μ A
$I_{(SNS)}$	Input bias current on SNS pin	$V_{(SNS)} = 5$ V			5	μ A
$I_{(TS)}$	Input bias current on TS pin	$V_{(TS)} = 5$ V			5	μ A
$I_{(COMP)}$	Input bias current on COMP pin	$V_{(COMP)} = 5$ V			5	μ A
BATTERY VOLTAGE REGULATION						
$V_{O(REG)}$	Output voltage	BQ2057, See (1) (2) (3)	4.059	4.10	4.141	V
		BQ2057C, See (1) (2) (3)	4.158	4.20	4.242	
		BQ2057T, See (1) (2) (3)	8.119	8.20	8.282	
		BQ2057W, See (1) (2) (3)	8.317	8.40	8.484	
CURRENT REGULATION						
$V_{(SNS)}$	Current regulation threshold	BQ2057 and BQ2057C, High-side current sensing configuration	95.4	105	115.5	mV
		BQ2057T and BQ2057W, High-side current sensing configuration	103.6	125	137.5	
		BQ2057 and BQ2057C, Low-side current sensing configuration	100	110	121	
		BQ2057T and BQ2057W, Low-side current sensing configuration	108.1	130	143	
CHARGE TERMINATION DETECTION						
$I_{(TERM)}$	Charge termination current detect threshold	Voltage at pin SNS, relative to V_{CC} for high-side sensing, and to V_{SS} for low-side sensing, $0^{\circ}\text{C} \leq T_A \leq 50^{\circ}\text{C}$	-30	-14	-4	mV
TEMPERATURE COMPARATOR						
$V_{(TS1)}$	Lower temperature threshold	TS pin voltage	29.1	30	30.9	%VCC
$V_{(TS2)}$	Upper temperature threshold		58.3	60	61.8	
PRECHARGE COMPARATOR						
$V_{(min)}$	Precharge threshold	BQ2057	2.94	3	3.06	V
		BQ2057C	3.04	3.1	3.16	
		BQ2057T	5.9	6.1	6.22	
		BQ2057W	6.18	6.3	6.43	
PRECHARGE CURRENT REGULATION						
$I_{(PRECHG)}$	Precharge current regulation	Voltage at pin SNS, relative to V_{CC} for high-side sensing, and to V_{SS} for low-side sensing, $0^{\circ}\text{C} \leq T_A \leq 50^{\circ}\text{C}$		13		mV
		Voltage at pin SNS, relative to V_{CC} for high-side sensing, $0^{\circ}\text{C} \leq T_A \leq 50^{\circ}\text{C}$, $V_{CC} = 5$ V	3	13	22	mV
V_{RCH} COMPARATOR (Battery Recharge Threshold)						
$V_{(RCH)}$	Recharge threshold	BQ2057 and BQ2057C	$V_{O(REG)} - 98$ mV	$V_{O(REG)} - 100$ mV	$V_{O(REG)} - 102$ mV	V
		BQ2057T and BQ2057W	$V_{O(REG)} - 196$ mV	$V_{O(REG)} - 200$ mV	$V_{O(REG)} - 204$ mV	V
CHARGE-RATE COMPENSATION (AutoComp)						
$G_{(COMP)}$	AutoComp gain	$V_{(BAT)} + 0.3$ V $\leq V_{CC} \leq V_{CC(max)}$, BQ2057, BQ2057C, BQ2057T, BQ2057W	1.87	2.2	2.53	V/V
		$V_{(BAT)} + 0.3$ V $\leq V_{CC} \leq V_{CC(max)}$, BQ2057T and BQ2057W in low-side sensing configuration	2.09	2.4	2.76	
STAT PIN						

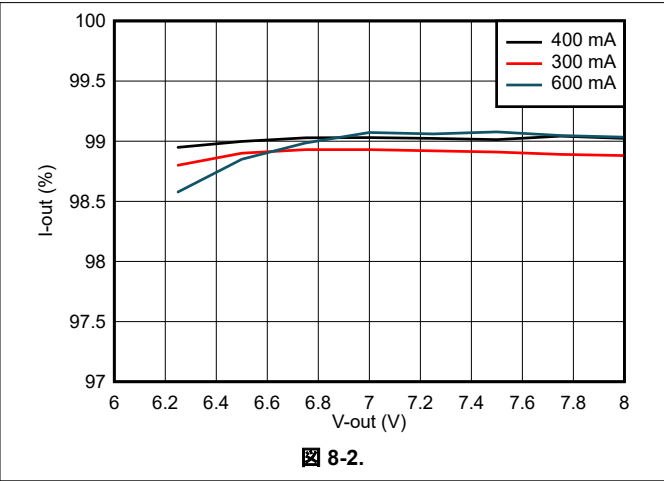
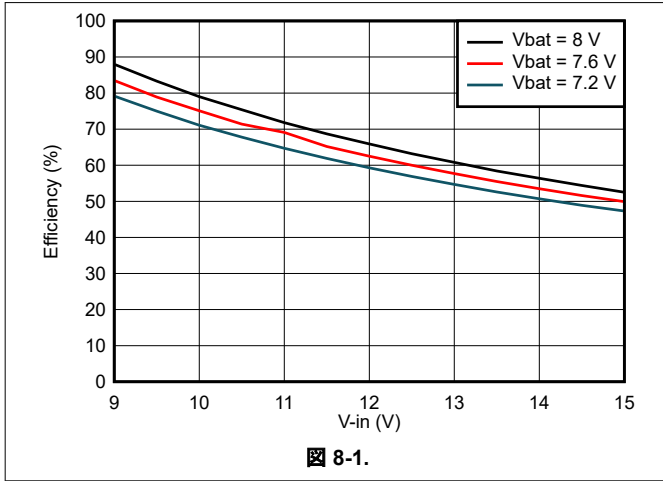
8.5 Electrical Characteristics (continued)

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$V_{OL(STAT)}$	Output (low) voltage	$I_{OL} = 10 \text{ mA}$			0.7	V
$V_{OH(STAT)}$	Output (high) voltage	$I_{OH} = 5 \text{ mA}$	$V_{CC} - 0.5$			
CC PIN						
$V_{OL(CC)}$	Output low voltage	$I_{O(CC)} = 5 \text{ mA (sink)}$			1.5	V
$I_{O(CC)}$	Sink current	Not to exceed power rating specification (P_D)	5		40	mA

- (1) For high-side current sensing configuration.
- (2) For low-side current sensing configuration, the tolerance is $\pm 1\%$ for $T_A = 25^\circ\text{C}$ and $\pm 1.2\%$ for $-20^\circ\text{C} \geq T_A \geq 70^\circ\text{C}$.
- (3) $V_{(BAT)} + 0.3 \text{ V} \leq V_{CC} \leq V_{CC(max)}$

8.6 Typical Characteristics

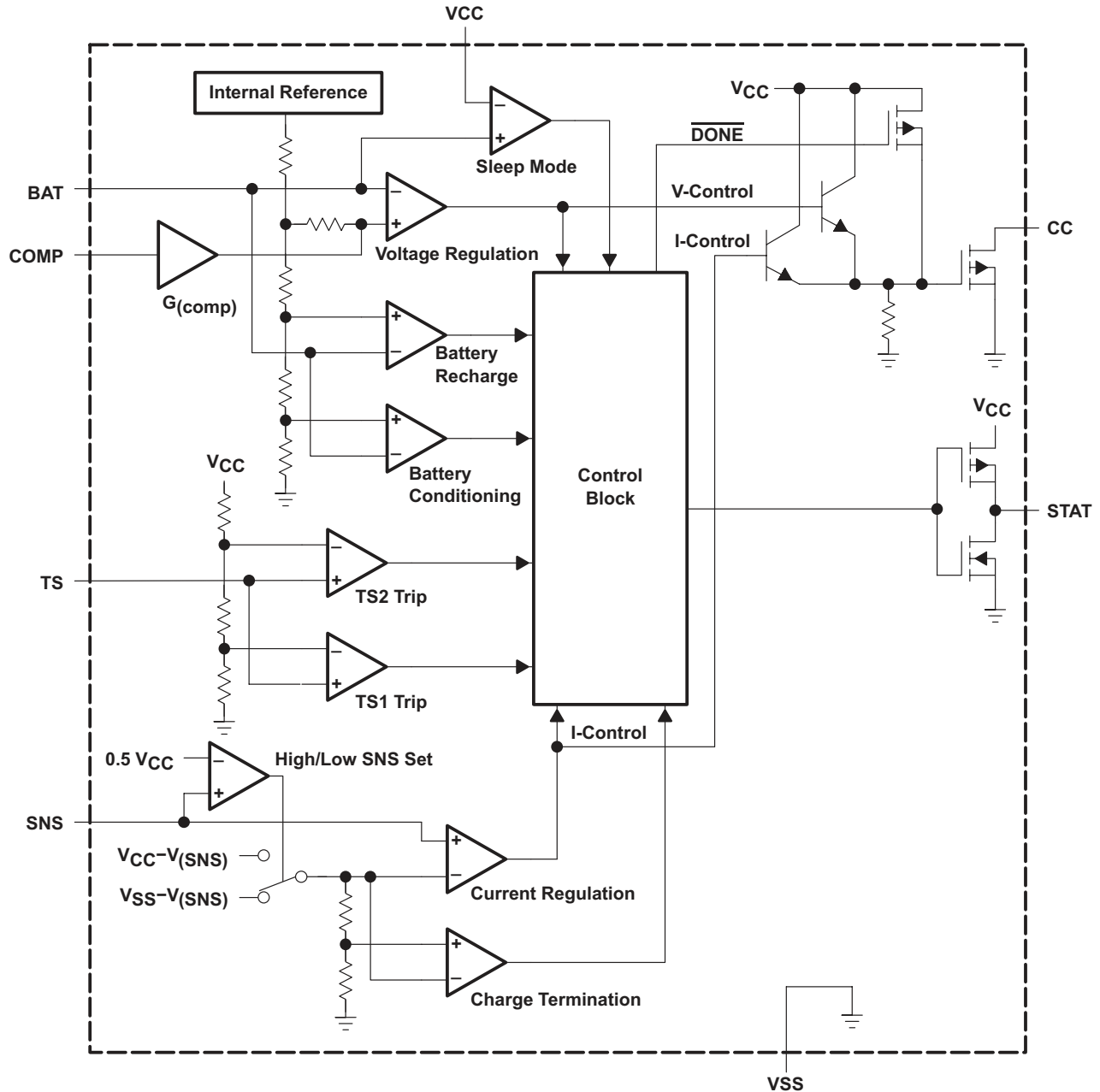


9 Detailed Description

9.1 Overview

Descriptions of the devices are presented in the following sections.

9.2 Functional Block Diagram



9.3 Feature Description

9.3.1 Current-Sense Input

Battery current is sensed via the voltage developed on this pin by an external sense resistor. The external resistor can be placed on either the high or low side of the battery. (See schematics for details.)

9.3.2 Battery-Voltage Input

Voltage sense-input tied directly to the positive side of the battery.

9.3.3 Temperature Sense Input

Input for an external battery-temperature monitoring circuit. Connecting this input to VCC/2 disables this feature.

9.3.4 Charge-status Output

Three-state indication of charge in progress, charge complete, and temperature fault or sleep mode.

9.3.5 Charge-Control Output

Source-follower output that drives an external pass-transistor (PNP or P-channel MOSFET) for current and voltage regulation.

9.3.6 Charge-Rate Compensation Input

Sets the charge-rate compensation level. The voltage-regulation output may be programmed to vary as a function of the charge current delivered to the battery.

9.3.7 Supply Voltage Input

Power supply input and current reference for high-side sensing configuration.

10 Application and Implementation

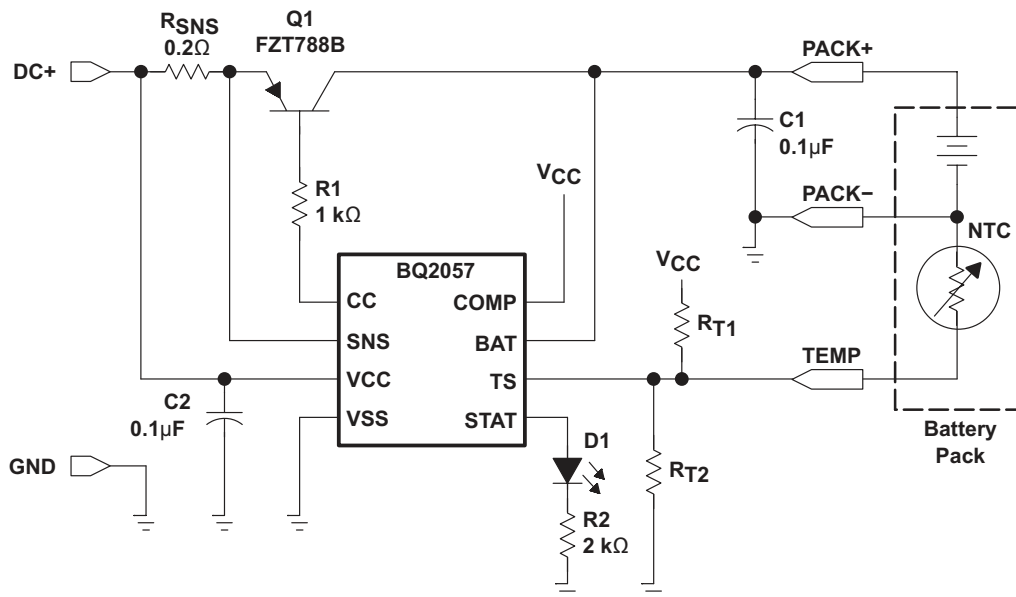
注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

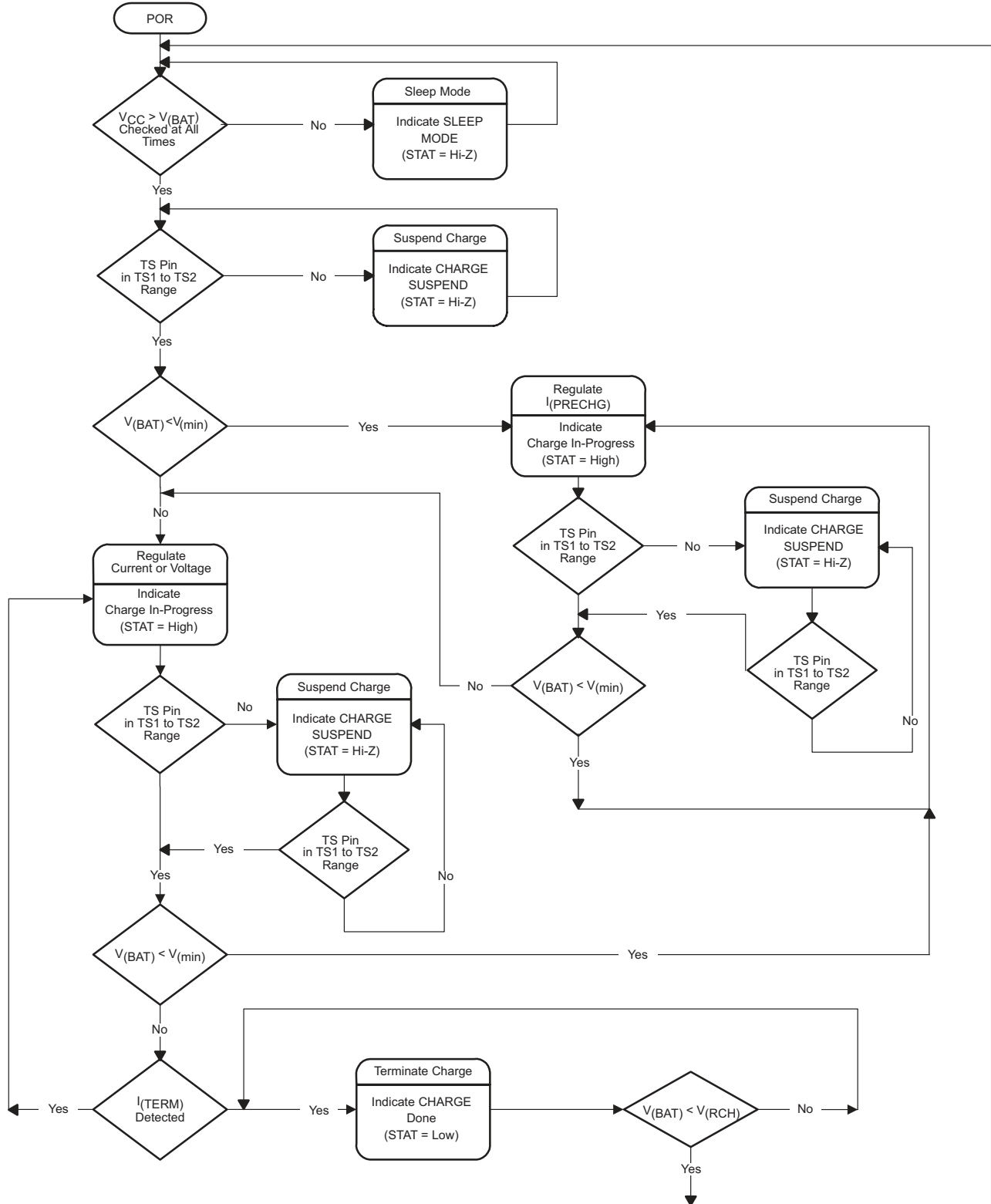
10.1 Application Information

10.1.1 Functional Description

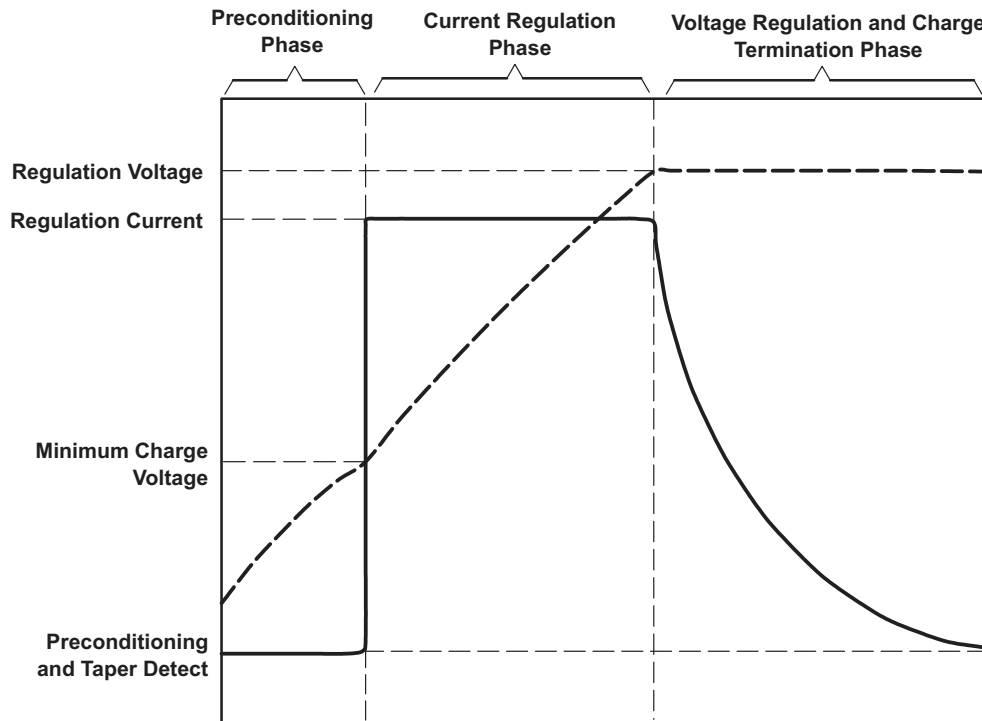
The BQ2057 is an advanced linear charge controller for single or two-cell Li-Ion or Li-Pol applications. [10-1](#) shows the schematic of charger using a PNP pass transistor. [10-2](#) is an operational state diagram, and [10-3](#) is a typical charge profile. [10-4](#) shows the schematic of a charger using P-channel MOSFET.



10-1. Low Dropout Single- or Two-Cell Li-Ion/Li-Pol Charger




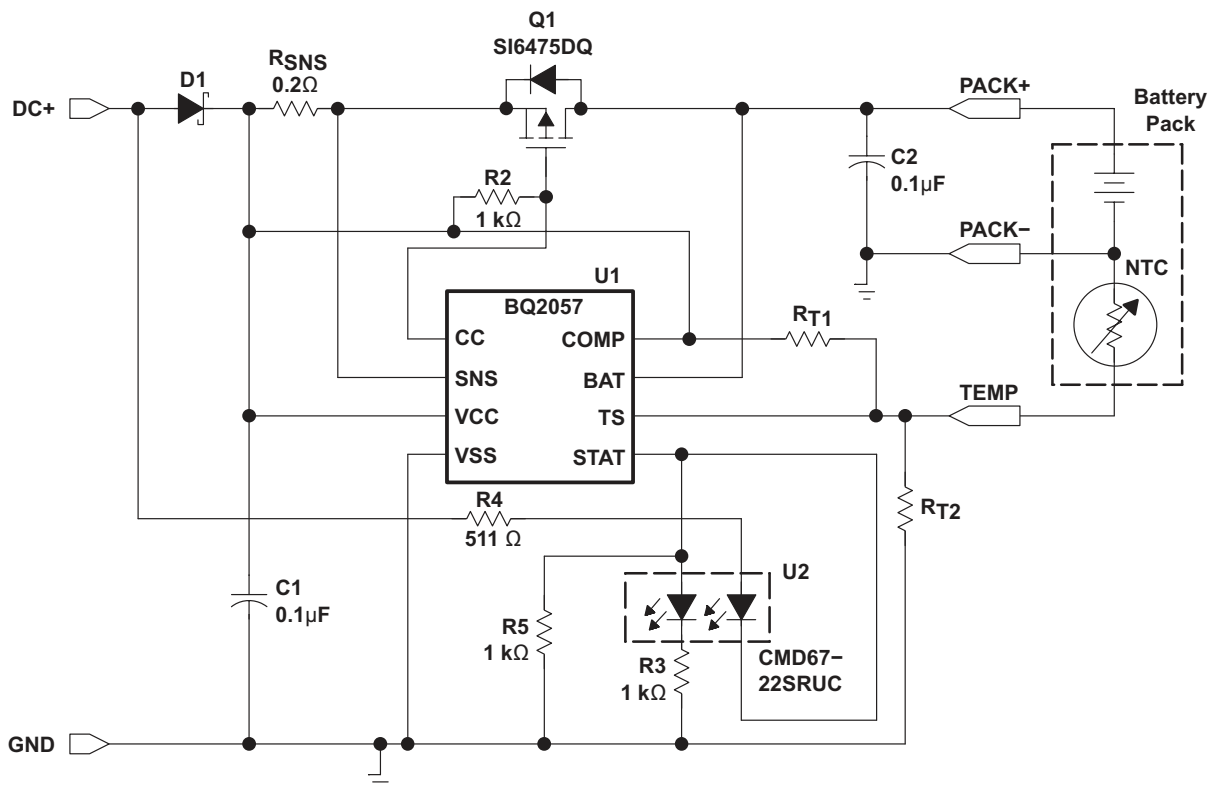
10-2. Operation Flowchart



 **10-3. Typical Charge Profile**

10.1.2 Qualification and Precharge

When power is applied, the BQ2057 starts a charge-cycle if a battery is already present or when a battery is inserted. Charge qualification is based on battery temperature and voltage. The BQ2057 suspends charge if the battery temperature is outside the $V_{(TS1)}$ to $V_{(TS2)}$ range and suspends charge until the battery temperature is within the allowed range. The BQ2057 also checks the battery voltage. If the battery voltage is below the precharge threshold $V_{(min)}$, the BQ2057 uses precharge to condition the battery. The conditioning charge rate $I_{(PRECHG)}$ is set at approximately 10% of the regulation current. The conditioning current also minimizes heat dissipation in the external pass-element during the initial stage of charge. See  10-3 for a typical charge-profile.



☒ 10-4. 0.5-A Charger Using P-Channel MOSFET

10.1.3 Current Regulation Phase

The BQ2057 regulates current while the battery-pack voltage is less than the regulation voltage, $V_{O(REG)}$. The BQ2057 monitors charge current at the SNS input by the voltage drop across a sense-resistor, R_{SNS} , in series with the battery pack. In high-side current sensing configuration (see ☒ 10-5), R_{SNS} is between the VCC and SNS pins, and in low-side sensing (see ☒ 10-6) the R_{SNS} is between VSS (battery negative) and SNS (charger ground) pins. Charge-current feedback, applied through pin SNS, maintains a voltage of $V_{(SNS)}$ across the current sense resistor. Equation 1 calculates the value of the sense resistor:

$$R_{SNS} = \frac{V_{(SNS)}}{I_{O(REG)}} \quad (1)$$

Where $I_{O(REG)}$ is the desired charging current.

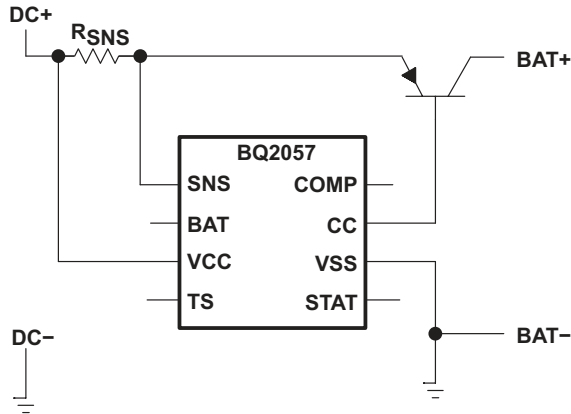


Figure 10-5. High-Side Current Sensing

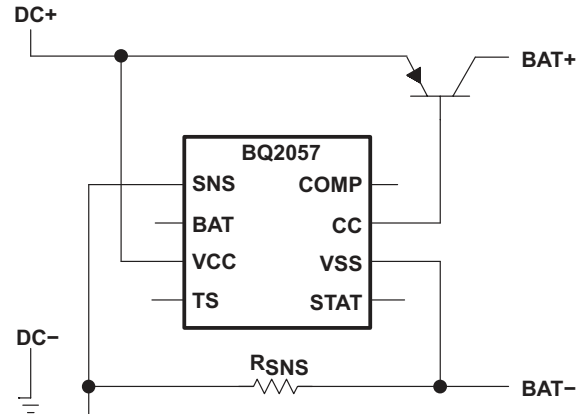


Figure 10-6. Low-Side Current Sensing

10.1.4 Voltage Regulation Phase

The voltage regulation feedback is through the BAT pin. This input is tied directly to the positive side of the battery pack. The BQ2057 monitors the battery-pack voltage between the BAT and VSS pins. The BQ2057 is offered in four fixed-voltage versions: 4.1 V, 4.2 V, 8.2 V, and 8.4 V.

Other regulation voltages can be achieved by adding a voltage divider between the positive and negative terminals of the battery pack and using BQ2057T or BQ2057W. The voltage divider presents scaled battery-pack voltage to BAT input. (See Figure 10-7 and Figure 10-8.) The resistor values RB1 and RB2 for the voltage divider are calculated by the following equation:

$$\frac{R_{B1}}{R_{B2}} = \left(N \times \frac{V_{(CELL)}}{V_{O(REG)}} \right) - 1 \quad (2)$$

Where:

N = Number of cells in series

V_(CELL) = Desired regulation voltage per cell

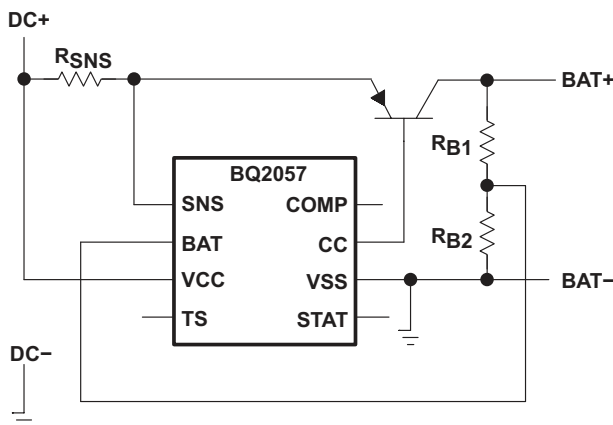


Figure 10-7. Optional Voltage Divider for Nonstandard Regulation Voltage, (High-Side Current Sensing)

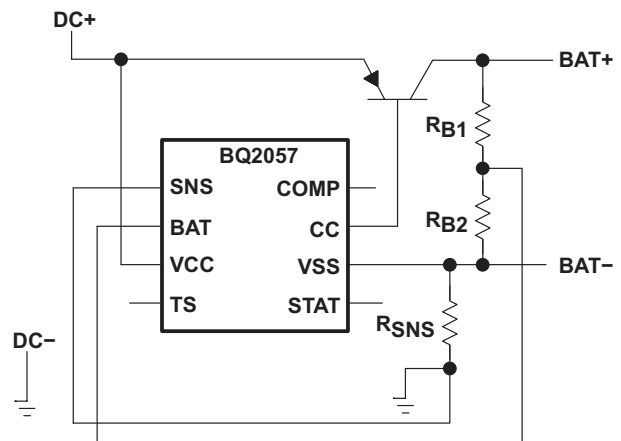


Figure 10-8. Optional Voltage Divider for Nonstandard Regulation Voltage, (Low-Side Current Sensing)

10.1.5 Charge Termination and Recharge

The BQ2057 monitors the charging current during the voltage-regulation phase. The BQ2057 declares a done condition and terminates charge when the current tapers off to the charge termination threshold, $I_{(TERM)}$. A new charge cycle begins when the battery voltage falls below the $V_{(RCH)}$ threshold.

10.1.6 Battery Temperature Monitoring

The BQ2057 continuously monitors temperature by measuring the voltage between the TS and VSS pins. A negative- or a positive-temperature coefficient thermistor (NTC, PTC) and an external voltage divider typically develop this voltage. (See [10-9](#).) The BQ2057 compares this voltage against its internal $V_{(TS1)}$ and $V_{(TS2)}$ thresholds to determine if charging is allowed. (See [10-10](#).) The temperature sensing circuit is immune to any fluctuation in V_{CC} , since both the external voltage divider and the internal thresholds ($V_{(TS1)}$ and $V_{(TS2)}$) are referenced to VCC.

The resistor values of $R_{(T1)}$ and $R_{(T2)}$ are calculated by the following equations:

For NTC Thermistors

$$R_{T1} = \frac{5 \times R_{TH} \times R_{TC}}{3 \times (R_{TC} - R_{TH})} \quad (3)$$

$$R_{T1} = \frac{5 \times R_{TH} \times R_{TC}}{3 \times (R_{TC} - R_{TH})} \quad (4)$$

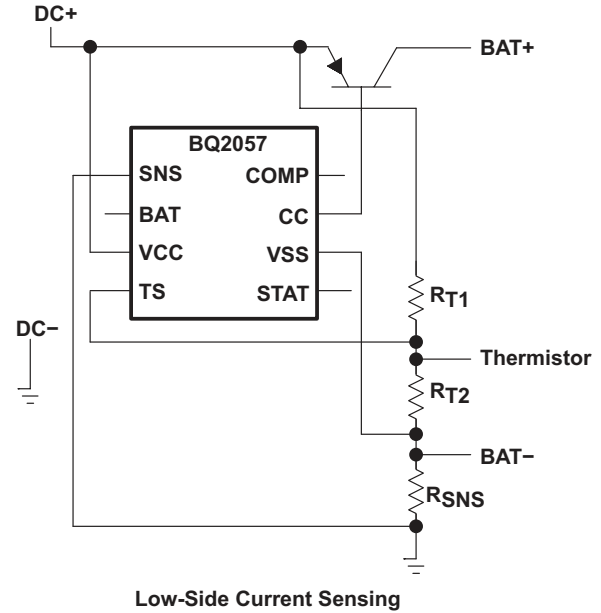
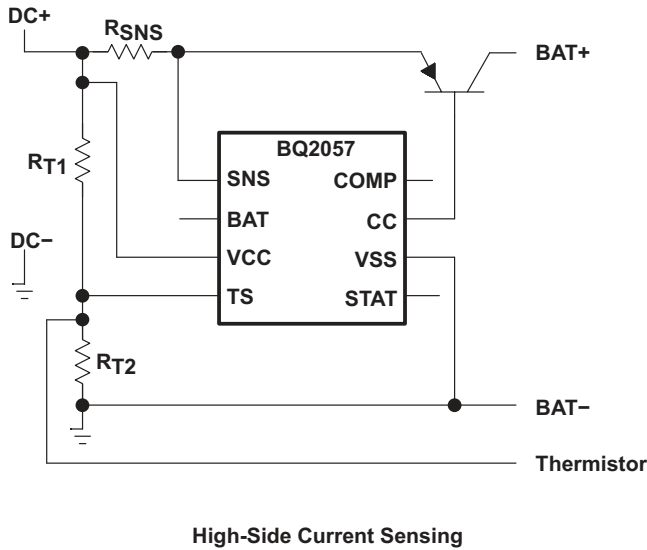
For PTC Thermistors

$$R_{T1} = \frac{5 \times R_{TH} \times R_{TC}}{3 \times (R_{TH} - R_{TC})} \quad (5)$$

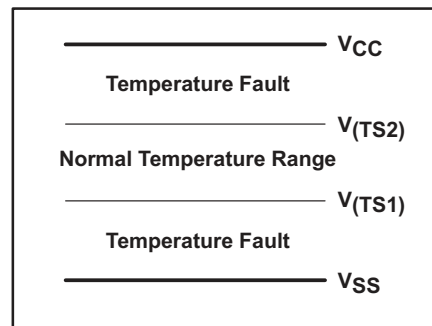
$$R_{T2} = \frac{5 \times R_{TH} \times R_{TC}}{\left[(2 \times R_{TH}) - (7 \times R_{TC}) \right]} \quad (6)$$

Where $R_{(TC)}$ is the cold temperature resistance and $R_{(TH)}$ is the hot temperature resistance of thermistor, as specified by the thermistor manufacturer.

R_{T1} or R_{T2} can be omitted if only one temperature (hot or cold) setting is required. Applying a voltage between the $V_{(TS1)}$ and $V_{(TS2)}$ thresholds to pin TS disables the temperature-sensing feature.



10-9. Temperature Sensing Circuits



10-10. BQ2057 TS Input Thresholds

10.1.7 Charge Inhibit Function

The TS pin can be used as charge-inhibit input. The user can inhibit charge by connecting the TS pin to VCC or VSS (or any level outside the $V_{(TS1)}$ to $V_{(TS2)}$ thresholds). Applying a voltage between the $V_{(TS1)}$ and $V_{(TS2)}$ thresholds to pin TS returns the charger to normal operation.

10.1.8 Charge Status Indication

The BQ2057 reports the status of the charger on the 3-state STAT pin. The following table summarized the operation of the STAT pin.

CONDITION	STAT PIN
Battery conditioning and charging	High
Charge complete (Done)	Low
Temperature fault or sleep mode	Hi-Z

The STAT pin can be used to drive a single LED (10-1), dual-chip LEDs (Figure 4) or for interface to a host or system processor (10-11). When interfacing the BQ2057 to a processor, the user can use an output port, as shown in 10-11, to recognize the Hi-Z state of the STAT pin. In this configuration, the user needs to read the input pin, toggle the output port and read the STAT pin again. In a Hi-Z condition, the input port always matches the signal level on the output port.

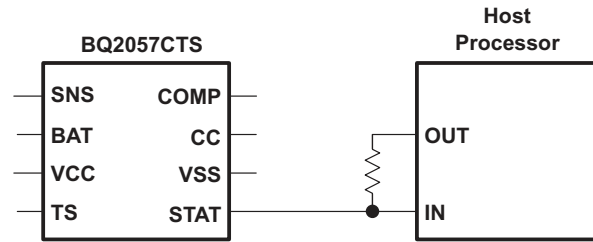


FIG 10-11. Interfacing the BQ2057 to a Host Processor

10.1.9 Low-power Sleep Mode

The BQ2057 enters the sleep mode if the VCC falls below the voltage at the BAT input. This feature prevents draining the battery pack during the absence of VCC.

10.1.10 Selecting an External Pass-Transistor

The BQ2057 is designed to work with both PNP transistor and P-channel MOSFET. The device should be chosen to handle the required power dissipation, given the circuit parameters, PCB layout and heat sink configuration. The following examples illustrate the design process for either device:

PNP transistor: Selection steps for a PNP bipolar transistor: Example: $V_I = 4.5\text{ V}$, $I_{(REG)} = 1\text{ A}$, 4.2-V single-cell Li-Ion (bq2057C). V_I is the input voltage to the charger and $I_{(REG)}$ is the desired charge current (see FIG 10-1).

1. Determine the maximum power dissipation, P_D , in the transistor. The worst case power dissipation happens when the cell voltage, $V_{(BAT)}$, is at its lowest (typically 3 V at the beginning of current regulation phase) and V_I is at its maximum.

Where V_{CS} is the voltage drop across the current sense resistor.

$$P_D = (V_I - V_{CS} - V_{(BAT)}) \times I_{REG}$$

$$P_D = (4.5 - 0.1 - 3) \times 1\text{ A}$$

$$P_D = 1.4\text{ W}$$

(7)

2. Determine the package size needed in order to keep the junction temperature below the manufacturer's recommended value, $T_{(J)max}$. Calculate the total theta, $\theta(^{\circ}\text{C}/\text{W})$, needed.

$$\theta_{JC} = \frac{(T_{(J)max} - T_{A(max)})}{P_D}$$

$$\theta_{JC} = \frac{(150 - 40)}{1.4}$$

$$\theta_{JC} = 78^{\circ}\text{C} / \text{W}$$

(8)

Now choose a device package with a theta at least 10% below this value to account for additional thetas other than the device. A SOT223 package, for instance, has typically a theta of $60^{\circ}\text{C}/\text{W}$.

3. Select a collector-emitter voltage, $V_{(CE)}$, rating greater than the maximum input voltage. A 15-V device will be adequate in this example.
4. Select a device that has at least 50% higher drain current I_C rating than the desired charge current $I_{(REG)}$.
5. Using Equation 9, calculate the minimum beta (β or h_{FE}) needed:

$$\beta_{min} = \frac{I_{CMAX}}{I_B}$$

$$\beta_{min} = \frac{1}{0.035}$$

$$\beta_{min} = 28$$

(9)

where $I_{\max(C)}$ is the maximum collector current (in this case same as $I_{(REG)}$), and I_B is the base current (chosen to be 35 mA in this example).

注

The beta of a transistor drops off by a factor of 3 over temperature and also drops off with load. Therefore, note the beta of device at $I_{(REG)}$ and the minimum ambient temperature when choosing the device. This beta should be larger than the minimum required beta.

Now choose a PNP transistor that is rated for $V_{(CE)} \geq 15$ V, $\theta_{JC} \leq 78^\circ\text{C/W}$, $I_C \geq 1.5$ A, $\beta_{\min} \geq 28$ and that is in a SOT223 package.

P-channel MOSFET: Selection steps for a P-channel MOSFET: Example: $V_I = 5.5$ V, $I_{(REG)} = 500$ mA, 4.2-V single-cell Li-Ion (BQ2057C). V_I is the input voltage to the charger and $I_{(REG)}$ is the desired charge current. (See [10-4.](#))

- Determine the maximum power dissipation, P_D , in the transistor.
The worst case power dissipation happens when the cell voltage, $V_{(BAT)}$, is at its lowest (typically 3 V at the beginning of current regulation phase) and V_I is at its maximum.
Where V_D is the forward voltage drop across the reverse-blocking diode (if one is used), and V_{CS} is the voltage drop across the current sense resistor.

$$P_D = (V_I - V_D - V_{(CS)} - V_{(BAT)}) \times I_{(REG)}$$

$$P_D = (5.5 - 0.4 - 0.1 - 3) \times 0.5 \text{ A}$$

$$P_D = 1 \text{ W} \tag{10}$$

- Determine the package size needed in order to keep the junction temperature below the manufacturer's recommended value, T_{JMAX} . Calculate the total theta, $\theta(^{\circ}\text{C/W})$, needed.

$$\theta_{JC} = \frac{(T_{\max(J)} - T_{A(\max)})}{P_D}$$

$$\theta_{JC} = \frac{(150 - 40)}{1}$$

$$\theta_{JC} = 110^\circ\text{C/W} \tag{11}$$

Now choose a device package with a theta at least 10% below this value to account for additional thetas other than the device. A TSSOP-8 package, for instance, has typically a theta of 70°C/W .

- Select a drain-source voltage, $V_{(DS)}$, rating greater than the maximum input voltage. A 12-V device will be adequate in this example.
- Select a device that has at least 50% higher drain current (I_D) rating than the desired charge current $I_{(REG)}$.
- Verify that the available drive is large enough to supply the desired charge current.

$$V_{(GS)} = (V_D + V_{(CS)} + V_{OL(CC)}) - V_I$$

$$V_{(GS)} = (0.4 + 0.1 + 1.5) - 5.5$$

$$V_{(GS)} = -3.5 \tag{12}$$

Where $V_{(GS)}$ is the gate-to-source voltage, V_D is the forward voltage drop across the reverse-blocking diode (if one is used), and V_{CS} is the voltage drop across the current sense resistor, and $V_{OL(CC)}$ is the CC pin output low voltage specification for the BQ2057.

Select a MOSFET with gate threshold voltage, $V_{(GStH)}$, rating less than the calculated $V_{(GS)}$.

Now choose a P-channel MOSFET transistor that is rated for $V_{DS} \leq -15\text{ V}$, $\theta_{JC} \leq 110^\circ\text{C/W}$, $I_D \geq 1\text{ A}$, $V_{(GSth)} \geq -3.5\text{ V}$ and in a TSSOP package.

10.1.11 Selecting Input Capacitor


In most applications, all that is needed is a high-frequency decoupling capacitor. A 0.1- μF ceramic, placed in proximity to VCC and VSS pins, works well. The BQ2057 works with both regulated and unregulated external dc supplies. If a nonregulated supply is chosen, the supply unit should have enough capacitance to hold up the supply voltage to the minimum required input voltage at maximum load. If not, more capacitance must be added to the input of the charger.

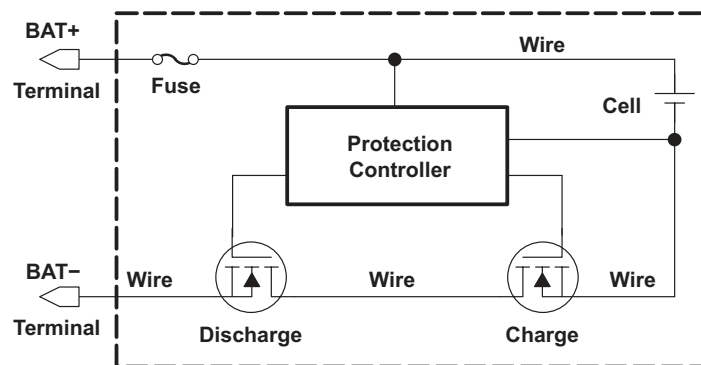
10.1.12 Selecting Output Capacitor

The BQ2057 does not require any output capacitor for loop stability. The user can add output capacitance in order to control the output voltage when a battery is not present. The charger quickly charges the output capacitor to the regulation voltage, but the output voltage decays slowly, because of the low leakage current on the BAT pin, down to the recharge threshold. Addition of a 0.1- μF ceramic capacitor, for instance, results in a 100-mV(pp) ripple waveform, with an approximate frequency of 25 Hz. Higher capacitor values can be used if a lower frequency is desired.


10.1.13 Automatic Charge-rate Compensation

To reduce charging time, the BQ2057 uses the proprietary AutoComp technique to compensate safely for internal impedance of the battery pack. The AutoComp feature is disabled by connecting the COMP pin to VCC in high-side current-sensing configuration, and to VSS in low-side current-sensing configuration. The COMP pin must not be left floating.

 10-12 outlines the major components of a single-cell Li-Ion battery pack. The Li-Ion battery pack consists of a cell, protection circuit, fuse, connector, current sense-resistors, and some wiring. Each of these components contains some resistance. Total impedance of the battery pack is the sum of the minimum resistances of all battery-pack components. Using the minimum resistance values reduces the odds for overcompensating. Overcompensating may activate the safety circuit of the battery pack.



 10-12. Typical Components of a Single-Cell Li-Ion Pack

Compensation is achieved through input pin COMP ( 10-13). A portion of the current-sense voltage, presented through this pin, is scaled by a factor of $G(\text{COMP})$ and summed with the regulation threshold, $V_{O(\text{REG})}$. This process increases the output voltage to compensate for the battery pack's internal impedance and for undesired voltage drops in the circuit.

AutoComp setup requires the following information:

- Total impedance of battery pack ($Z_{(\text{PACK})}$)
- Maximum charging current ($I_{(\text{REG})}$)

The voltage drop across the internal impedance of battery pack, $V_{(Z)}$, can then be calculated using [Equation 13](#):

$$V_{(Z)} = Z_{(\text{PACK})} \times I_{(\text{REG})} \quad (13)$$

The required compensation is then calculated using [Equation 14](#):

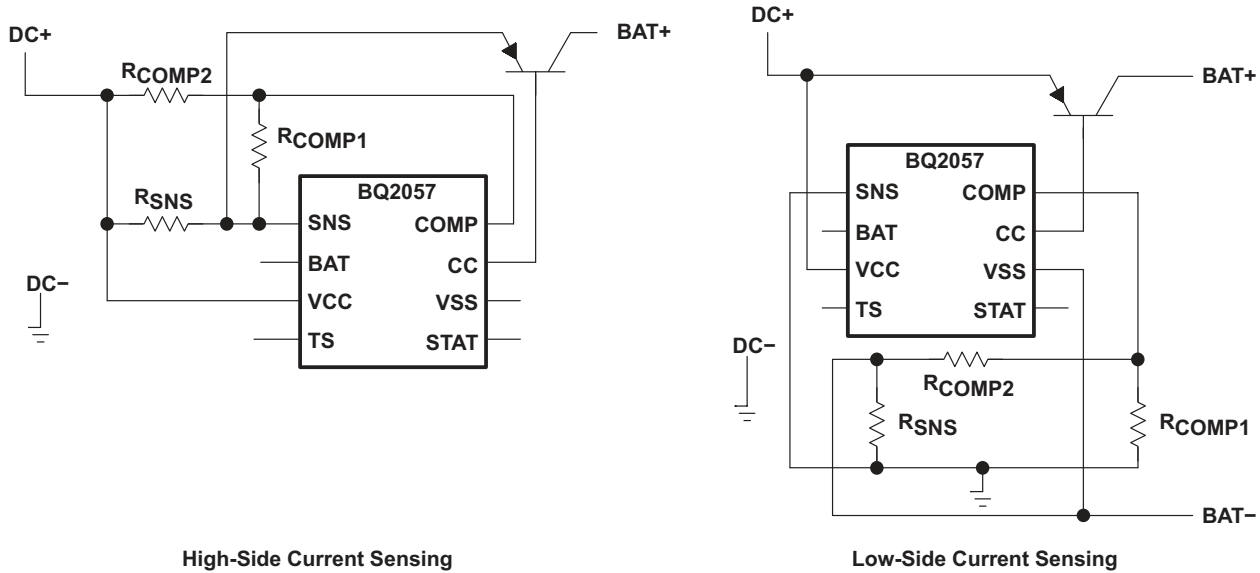
$$V_{(COMP)} = \frac{V_{(Z)}}{G_{(COMP)}}$$

$$V_{(PACK)} = V_{O(REG)} + (G_{(COMP)} \times V_{(COMP)}) \quad (14)$$

Where $V_{(COMP)}$ is the voltage on COMP pin. This voltage is referenced to VCC in high-side current sensing configuration and to VSS for low-side sensing. $V_{(PACK)}$ is the voltage across the battery pack.

The values of $R_{(COMP1)}$ and $R_{(COMP2)}$ can be calculated using [Equation 15](#):

$$\frac{V_{(COMP)}}{V_{(SNS)}} = \frac{R_{COMP2}}{R_{COMP1} + R_{COMP2}} \quad (15)$$



10-13. AutoComp Circuits

The following example illustrates these calculations:

Assume $Z_{(PACK)} = 100 \text{ m}\Omega$, $I_{(REG)} = 500 \text{ mA}$, high-side current sensing BQ2057C

$$V_{(Z)} = Z_{(PACK)} \times I_{(REG)}$$

$$V_{(Z)} = 0.1 \times 0.5$$

$$V_{(Z)} = 50 \text{ mV} \quad (16)$$

$$V_{(COMP)} = \frac{V_{(Z)}}{G_{(COMP)}}$$

$$V_{(COMP)} = \frac{0.05}{2.2}$$

$$V_{(COMP)} = 22.7 \text{ mV}$$

Let $R_{COMP2} = 10 \text{ k}\Omega$ (17)

$$R_{COMP1} = \frac{R_{COMP2} \times (V_{(SNS)} - V_{(COMP)})}{V_{(COMP)}}$$

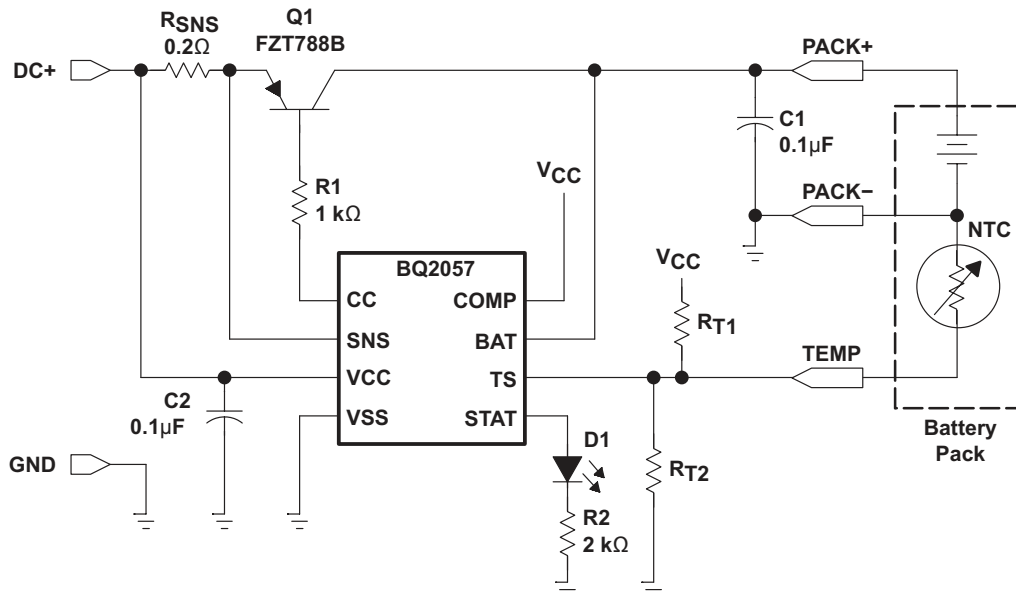
$$R_{COMP1} = 10k \times \frac{(105 \text{ mV} - 22.7 \text{ mV})}{22.7 \text{ mV}}$$


$$R_{COMP1} = 36.25 \text{ k}\Omega$$

(18)

Use the closest standard value (36.0 kΩ) for R_{COMP1}.

10.2 Typical Application



 10-14. Low Dropout Single- or Two-Cell Li-Ion/Li-Pol Charger

10.2.1 Design Requirements

The design requirements include the following:

- Supply voltage = 12 V
- Dual cell Li-ion 8.2 V
- Fast charge current = 600 mA
 - High-side current sense
- Termination current = 10% (default)
- Precharge current = 10% (default)
- TS – Battery temperature sense = 10 kΩ (103AT, NTC)
 - 0°C cold and 60°C hot

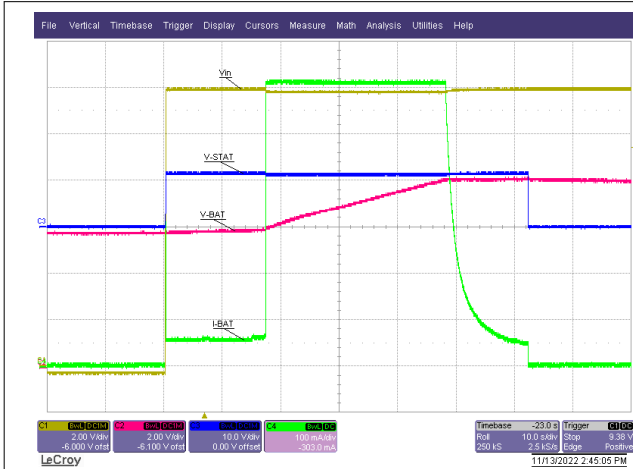
10.2.2 Detailed Design Procedure

The detailed design procedure is listed below:

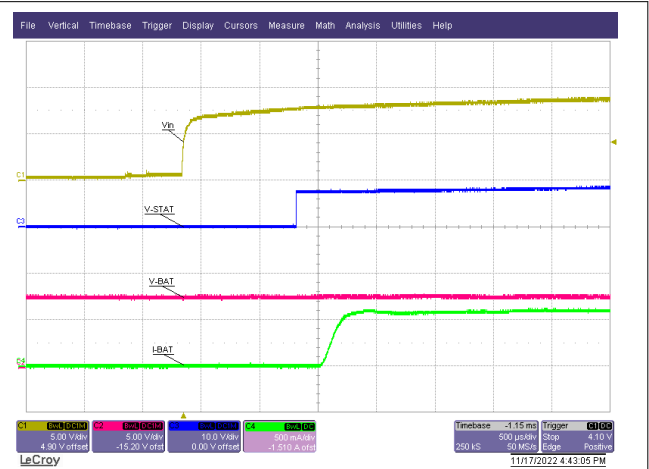
- Single cell Li-ion, 8.2 V - BQ2057T
- Pass transistor
 - For PNP BJT, see section 10.1.10 PNP transistor
 - For P-Type MOSFET, see section 10.1.10 P-channel MOSFET
- Fast charge current, see equation 1
 - $R_{sns} = V_{sns} / I_{out} = 125 \text{ mV} / 600 \text{ mA} = 0.2 \Omega$
- Termination Current default to 10% of fast charge current

- Pre-Charge Current default to 10% of fast charge current.
- TS – apply Equations 3 and 4 to calculate RT1 and RT2
 - RT1 = 5600 Ω (5.62 kΩ), RT2 = 12326 Ω (12.4 kΩ)

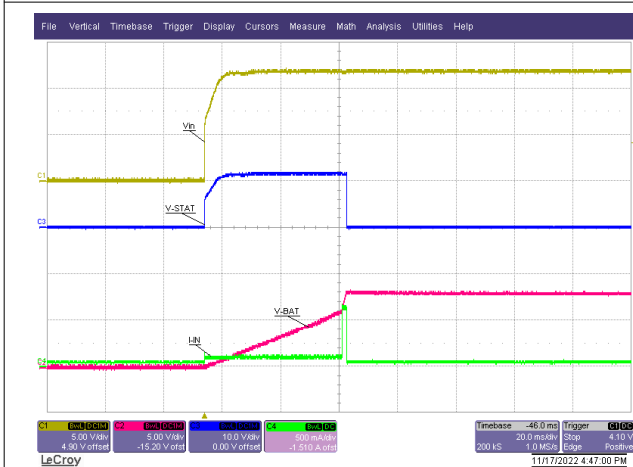
10.2.3 Application Curves



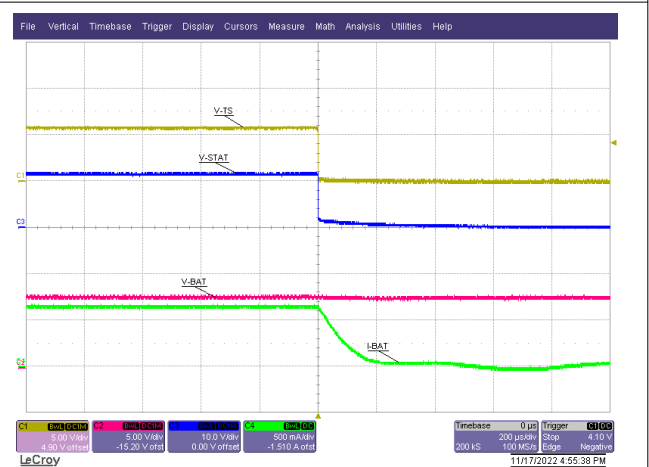
10-15. Charge Profile with Battery Simulator



10-16. Charge Profile with Battery Simulator - STAT



10-17. Power On - No Battery



10-18. Shutdown - TS Pin Low

11 Power Supply Recommendations

The devices are designed to operate from an input voltage supply range between 4.5 V and 15 V and current capability of at least the maximum designed charge current. This input supply should be well regulated. If located more than a few inches from the device, VCC and GND terminals, a larger capacitor is recommended.

12 Layout

12.1 Layout Guidelines

12.1.1 Power FET

The external pass PNP transistor or P-channel MOSFET will have high thermal rise, good heat sinking will be required.

12.1.2 Current Sense

The BQ2057 regulates current by sensing, on the SNS pin, the voltage drop developed across an external sense resistor. The sense resistor must be placed between the supply voltage (V_{CC}) and the input of the IC (IN pins).

12.1.3 Voltage Sense

To achieve maximum voltage regulation accuracy, the BQ2057 uses the feedback on the BAT pin. Externally, this pin should be connected as close to the battery cell terminals as possible. For additional safety, a 10-k Ω internal pullup resistor is connected between the VSENSE and OUT pins.

12.1.4 Enable (TS)

The TS pin can be used as charge-inhibit. Pulling up to V_{CC} or pulling down to V_{SS} places the device in a low-power standby mode.

12.2 Layout Example

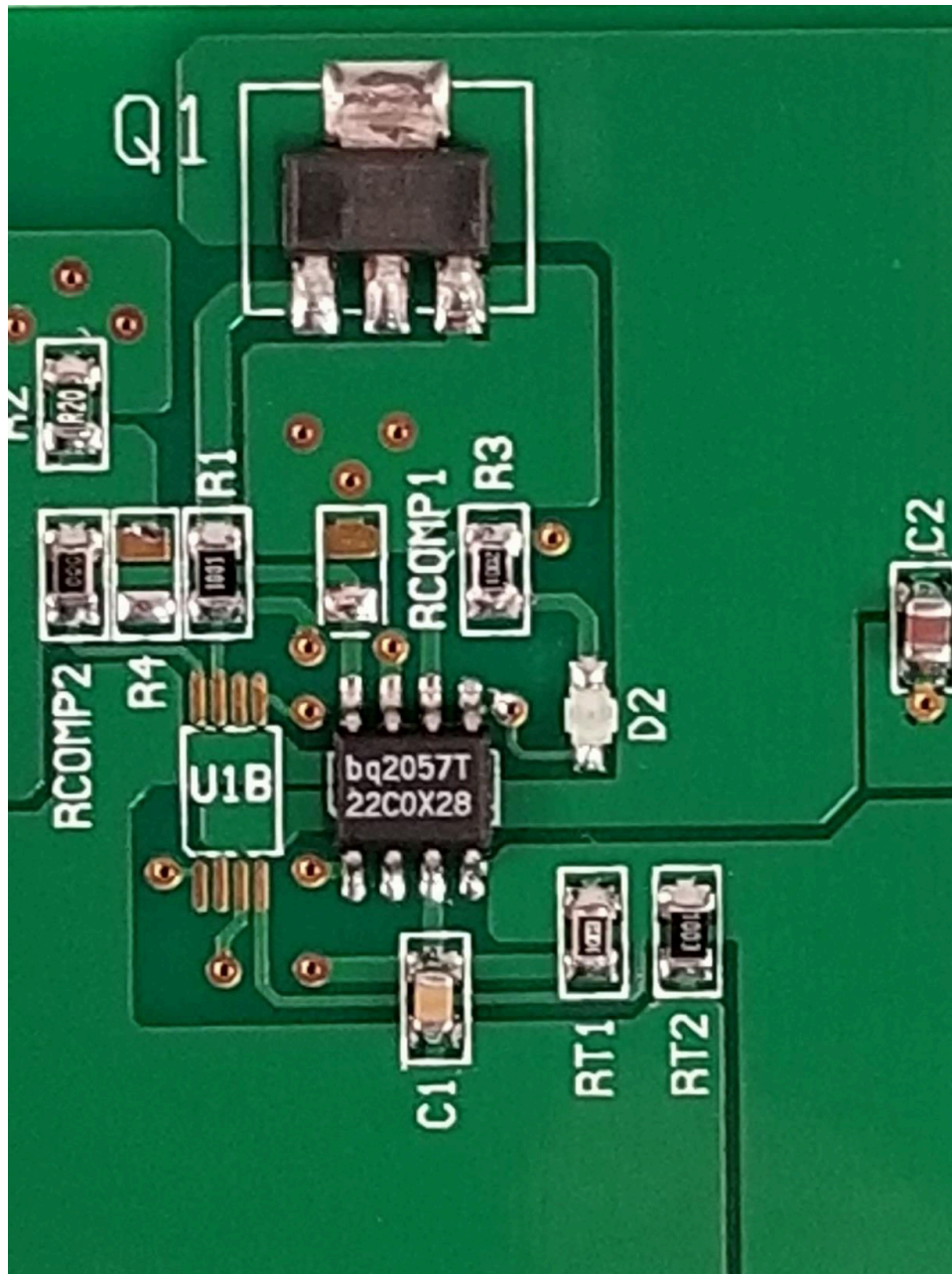
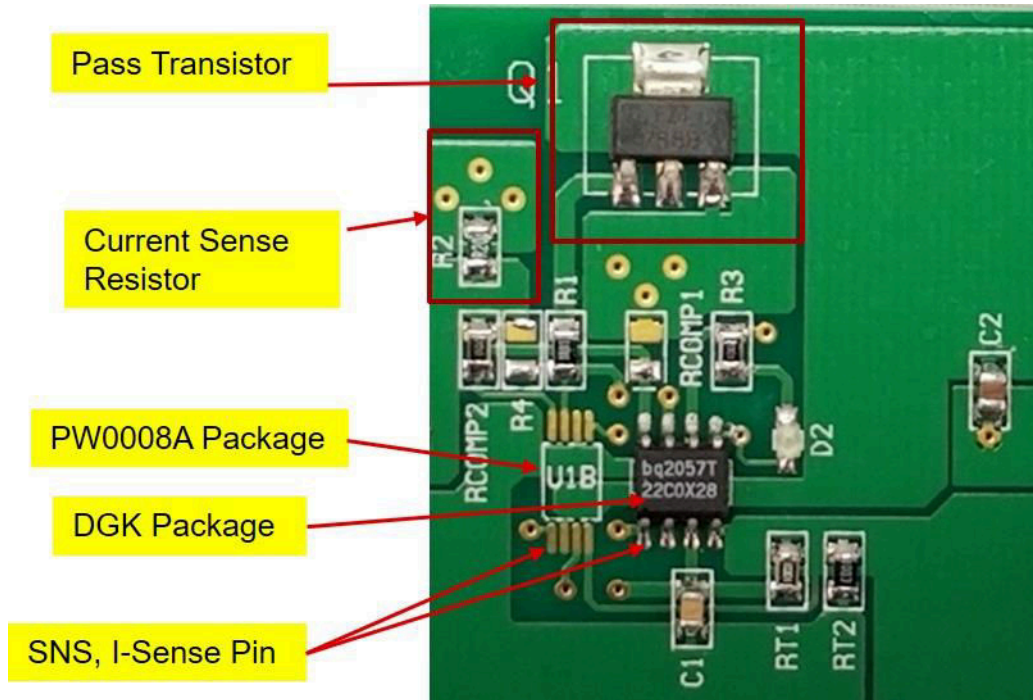


图 12-1. Layout Example



☒ 12-2. Layout Example

13 Device and Documentation Support

13.1 Device Support

13.1.1 サード・パーティ製品に関する免責事項

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13.6 用語集

[テキサス・インスツルメンツ用語集](#)

この用語集には、用語や略語の一覧および定義が記載されています。

14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
BQ2057CDGK	Active	Production	VSSOP (DGK) 8	80 TUBE	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-20 to 70	2057C
BQ2057CDGK.A	Active	Production	VSSOP (DGK) 8	80 TUBE	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-20 to 70	2057C
BQ2057CDGKR	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-20 to 70	2057C
BQ2057CDGKR.A	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-20 to 70	2057C
BQ2057CSN	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-20 to 70	2057C
BQ2057CSN.A	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-20 to 70	2057C
BQ2057CSNTR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-20 to 70	2057C
BQ2057CSNTR.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-20 to 70	2057C
BQ2057CTS	Active	Production	TSSOP (PW) 8	150 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-20 to 70	2057C
BQ2057CTS.A	Active	Production	TSSOP (PW) 8	150 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-20 to 70	2057C
BQ2057CTSTR	Active	Production	TSSOP (PW) 8	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-20 to 70	2057C
BQ2057CTSTR.A	Active	Production	TSSOP (PW) 8	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-20 to 70	2057C

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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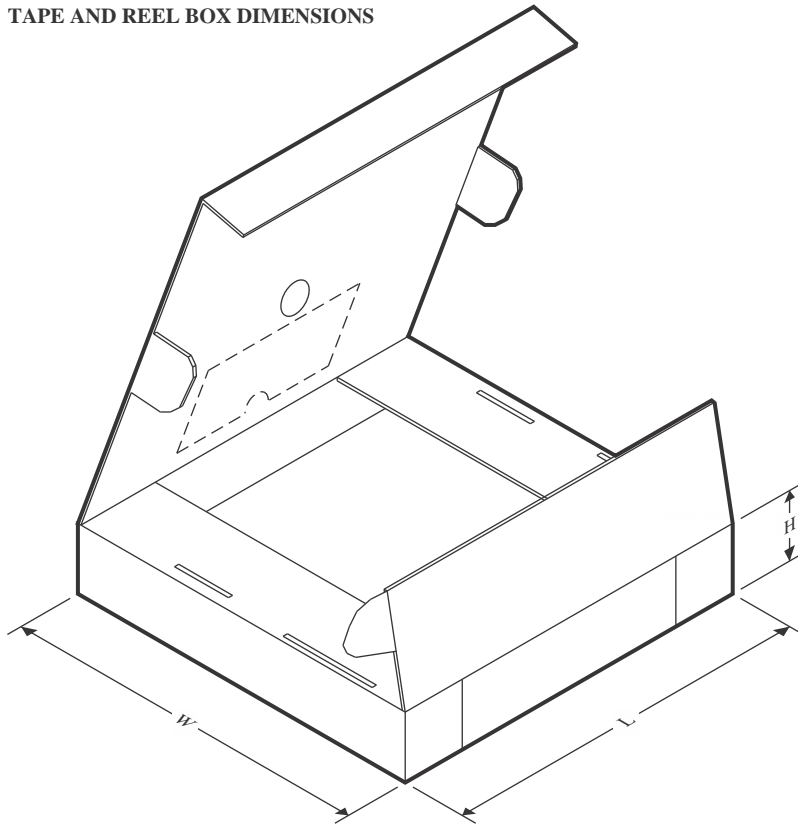
TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
BQ2057CDGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
BQ2057CSNTR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
BQ2057CTSTR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
BQ2057CDGKR	VSSOP	DGK	8	2500	353.0	353.0	32.0
BQ2057CSNTR	SOIC	D	8	2500	353.0	353.0	32.0
BQ2057CTSTR	TSSOP	PW	8	2000	353.0	353.0	32.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
BQ2057CDGK	DGK	VSSOP	8	80	330.2	6.6	3005	1.88
BQ2057CDGK.A	DGK	VSSOP	8	80	330.2	6.6	3005	1.88
BQ2057CSN	D	SOIC	8	75	506.6	8	3940	4.32
BQ2057CSN.A	D	SOIC	8	75	506.6	8	3940	4.32
BQ2057CTS	PW	TSSOP	8	150	508	8.5	3250	2.8
BQ2057CTS.A	PW	TSSOP	8	150	508	8.5	3250	2.8

DGK0008A



PACKAGE OUTLINE

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



4214862/A 04/2023

NOTES:

PowerPAD is a trademark of Texas Instruments.

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-187.

EXAMPLE BOARD LAYOUT

DGK0008A

™ VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 15X



SOLDER MASK DETAILS

4214862/A 04/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.
9. Size of metal pad may vary due to creepage requirement.

EXAMPLE STENCIL DESIGN

DGK0008A

TM VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
SCALE: 15X

4214862/A 04/2023

NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.



D0008A

PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4214825/C 02/2019

NOTES:

- Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed $.006$ [0.15] per side.
- This dimension does not include interlead flash.
- Reference JEDEC registration MS-012, variation AA.

EXAMPLE BOARD LAYOUT

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
 EXPOSED METAL SHOWN
 SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

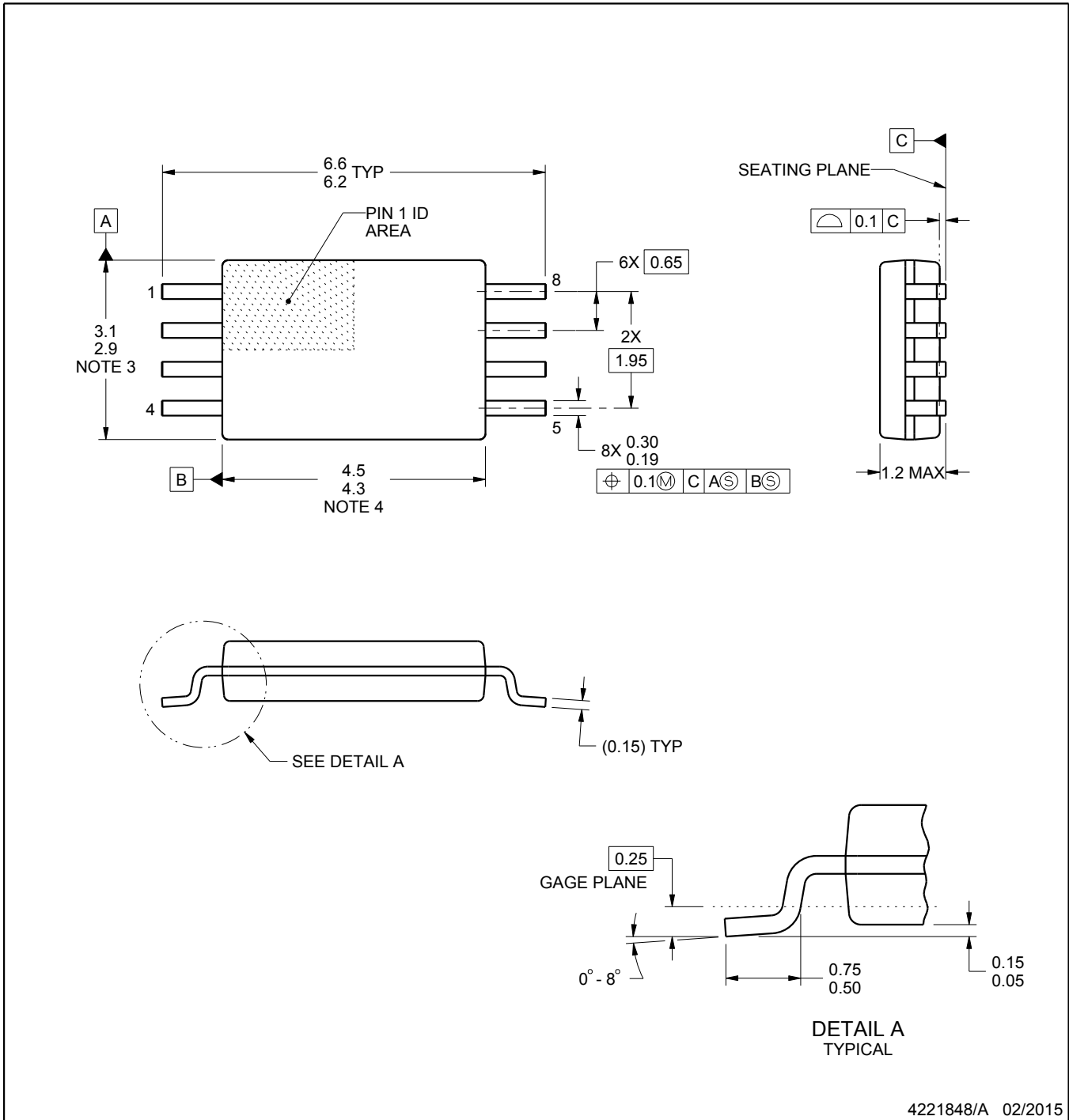
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PW0008A



PACKAGE OUTLINE
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4221848/A 02/2015

NOTES:

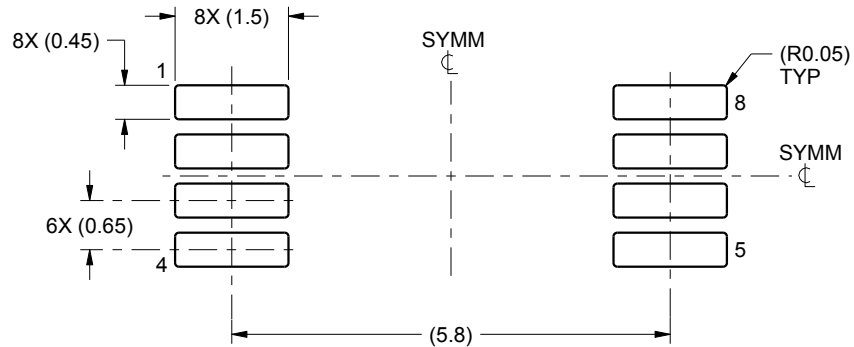
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153, variation AA.

EXAMPLE BOARD LAYOUT

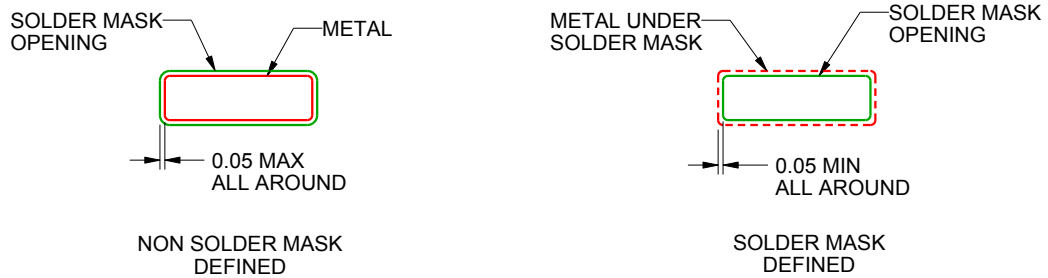
PW0008A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:10X



SOLDER MASK DETAILS
NOT TO SCALE

4221848/A 02/2015

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0008A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:10X

4221848/A 02/2015

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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最終更新日 : 2025 年 10 月